

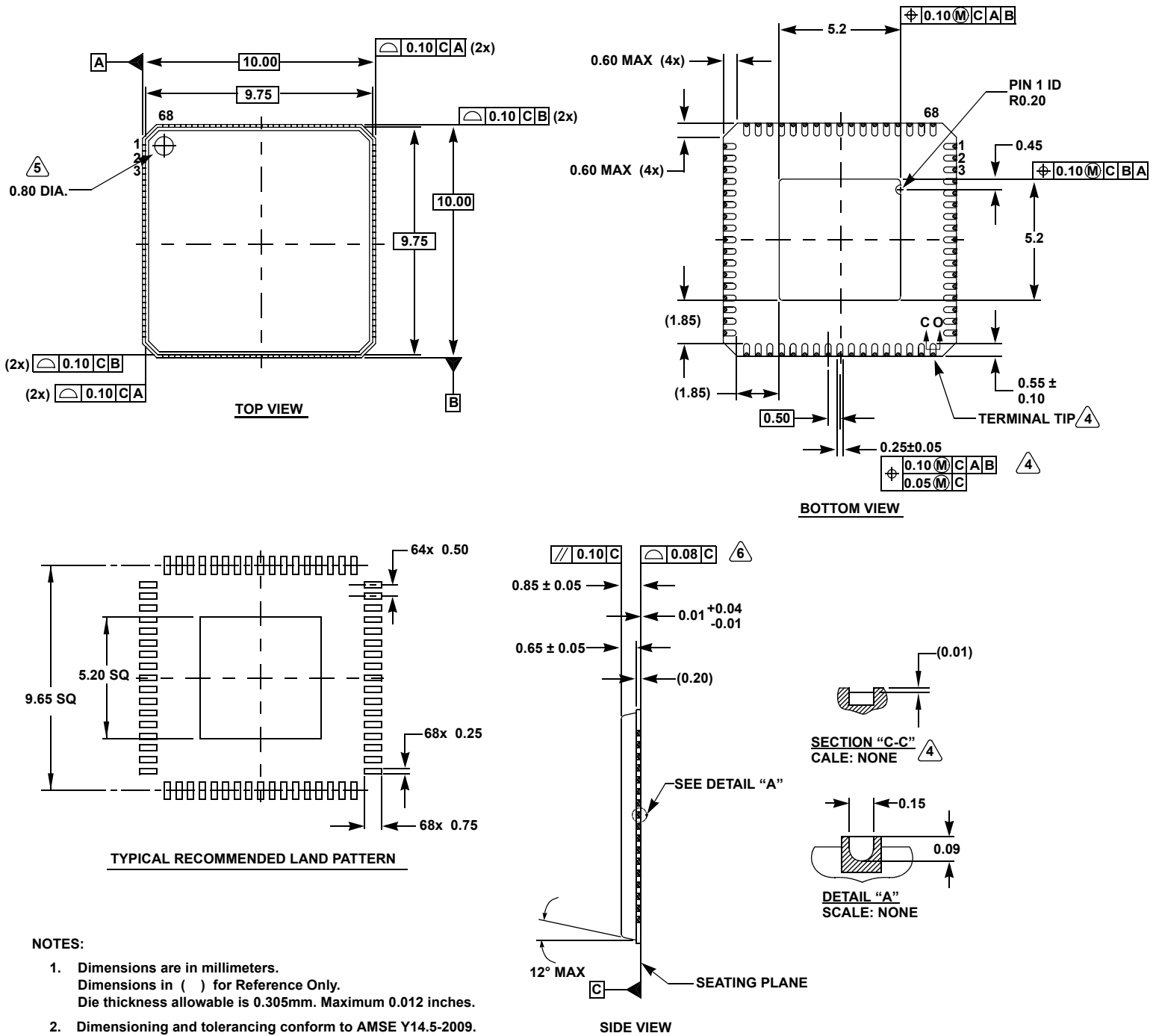
Plastic Packages for Integrated Circuits

Package Outline Drawing

L68.10x10D

68 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE (PUNCH QFN WITH WETTABLE FLANK)

Rev 0, 03/14



NOTES:

1. Dimensions are in millimeters.
Dimensions in () for Reference Only.
Die thickness allowable is 0.305mm. Maximum 0.012 inches.
2. Dimensioning and tolerancing conform to AMSE Y14.5-2009.
3. Unless otherwise specified, tolerance: Decimal ± 0.05.

4. Dimension applies to plated terminal and is measured between 0.15mm and 0.30mm from the terminal tip.

5. The Pin #1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body.

6. Unilateral coplanarity zone applies to the exposed pad as well as the terminals.